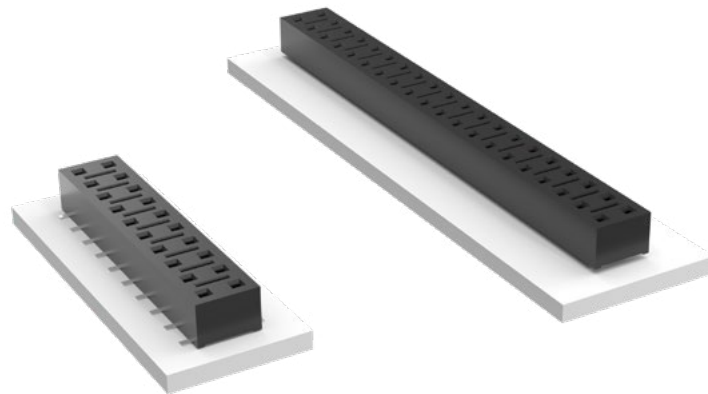


COST-EFFECTIVE RELIABLE SOCKET

(2.54 mm) .100" PITCH • HLE SERIES



HLE
Board Mates:
TSW, MTSW, DW, EW,
ZW, TLW, TSM, MTLW, HW

HLE	- 1	NO. PINS PER ROW	- 02	PLATING OPTION	- DV	TAIL OPTION	-	OTHER OPTION
-----	-----	---------------------	------	-------------------	------	----------------	---	-----------------

02 thru 50

-F
= Gold flash on
contact,
Matte Tin on tail

-L
= 10 μ " (0.25 μ m)
Gold on contact,
Matte Tin on tail

Leave blank for
Surface Mount
(Requires -BE for
Bottom Entry)

-TE
= Through-hole
Top Entry

-PE
= Through-hole
Pass-through
Entry
(Requires -BE for
Bottom Entry)

-BE
= Bottom Entry
(Not available
with -TE)

-A
= Alignment Pin
(4 positions min.)
Metal or plastic at
Samtec discretion
(Not available with
-TE, -PE & -LC)

-LC
= Locking Clip
(2 positions min.)
(Not available with -A)
(Manual placement
required)

-K
= (6.50 mm)
.256" DIA
Polyimide Film
Pick & Place Pad
(3 positions min.)
Not available
with -TE or
-PE tail option

-P
= Metal Pick
& Place Pad
(3 positions min.)

-TR
= Tape & Reel
(29 positions max.)

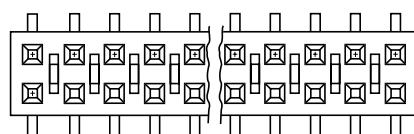
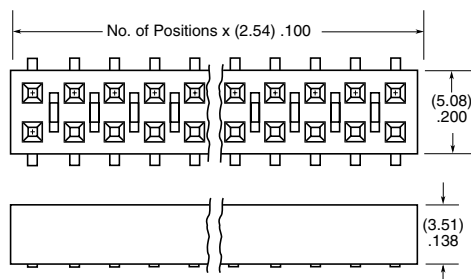
-FR
= Full Reel
Tape & Reel
(must order max.
quantity per reel;
contact Samtec for
quantity breaks)

SPECIFICATIONS

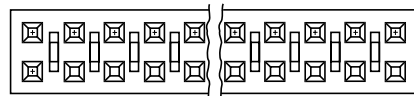
Insulator Material:
Black Liquid Crystal Polymer
Contact Material:
BeCu
Plating:
Au or Sn over
50 μ " (1.27 μ m) Ni
Current Rating (HLE/TSM):
4.1 A per pin
(2 pins powered)
Voltage Rating:
400 VAC
Operating Temp Range:
-55 °C to +125 °C
Insertion Depth:
(1.78 mm) .070" to
(3.43 mm) .135" pass-through,
or (2.59 mm) .102" min
plus board thickness for
bottom entry

PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (02-20)
(0.15 mm) .006" max (21-50)*
*(.004" stencil solution
may be available; contact
IPG@samtec.com)



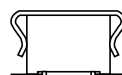
-PE



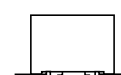
-TE

ALSO AVAILABLE

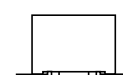
Other Platings
(MOQ Required)



-P



-LC



-A

Note:
Some lengths, styles and
options are non-standard,
non-returnable.